

1. General description

Planar passivated Silicon Controlled Rectifier (SCR) in a TO263 plastic package intended for use in applications requiring very high inrush current capability, high thermal cycling performance and high junction temperature capability ($T_{j(max)} = 150\text{ °C}$).

2. Features and benefits

- High junction operating temperature capability ($T_{j(max)} = 150\text{ °C}$)
- Very high current surge capability
- Planar passivated for voltage ruggedness and reliability
- High turn-on current rise $dI_T/dt = 150\text{ A}/\mu\text{s}$
- High noise immunity $dV_D/dt = 500\text{ V}/\mu\text{s}$ up to 150 °C
- High thermal cycling performance
- High voltage capability

3. Applications

- High voltage capability
- Protection circuits e.g. SMPS inrush current
- Motor control circuits and starters
- Voltage regulation
- Solid state relays

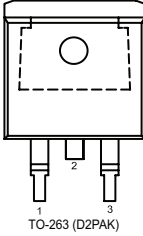

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Notes	Values			Unit
V_{DRM}	repetitive peak off-state voltage			800			V
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 131\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3		50			A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5		500			A
		half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$		550			A
T_j	junction temperature			-40 to 150			°C
Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7		-	-	15	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9		-	-	60	mA
V_T	on-state voltage	$I_T = 100\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10		-	-	1.65	V
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$; $T_j = 150\text{ °C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit		500	-	-	V/ μs

5. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode	 <p>TO-263 (D2PAK)</p>	 <p>sym037</p>
2	A	anode		
3	G	gate		
mb	A	mounting base; connected to anode		

6. Ordering information

Table 3. Ordering information

Type number	Package Name	Orderable part number	Packing method	Small packing quantity	Package version	Package issue date
TYN50B-800T	TO263	TYN50B-800TJ	Reel	800	TO263N	28-Sep-2016

7. Marking

Table 4. Marking codes

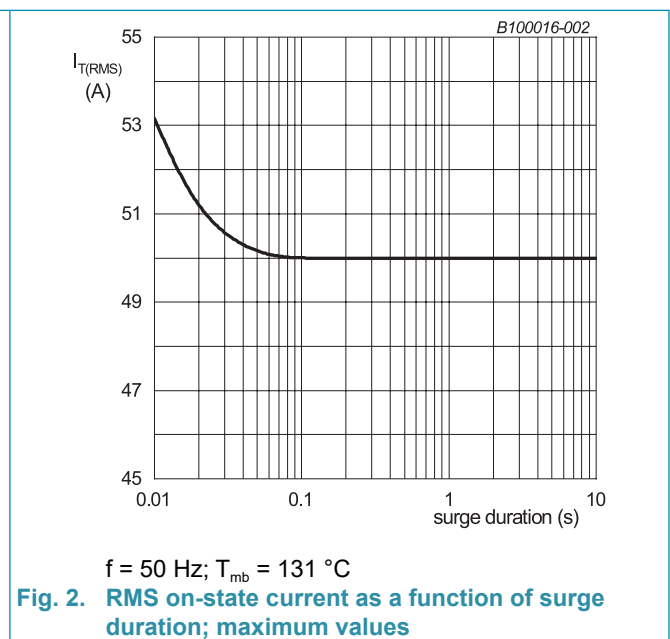
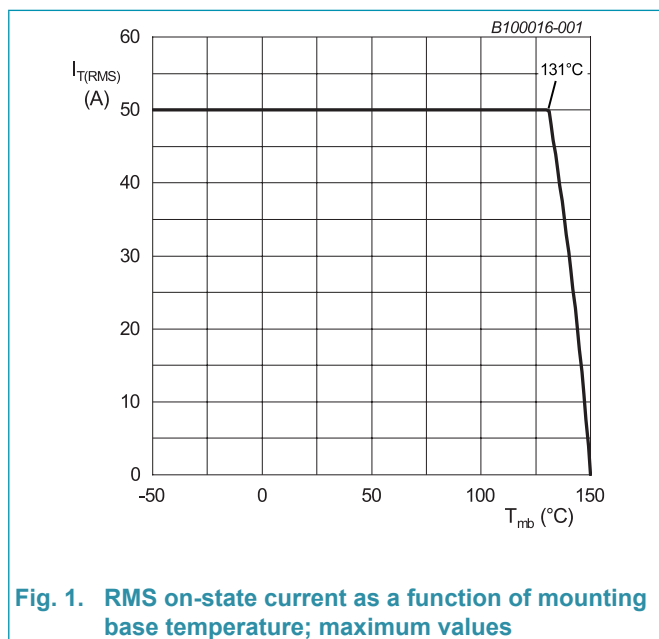
Type number	Marking codes
TYN50B-800T	TYN50B 800T

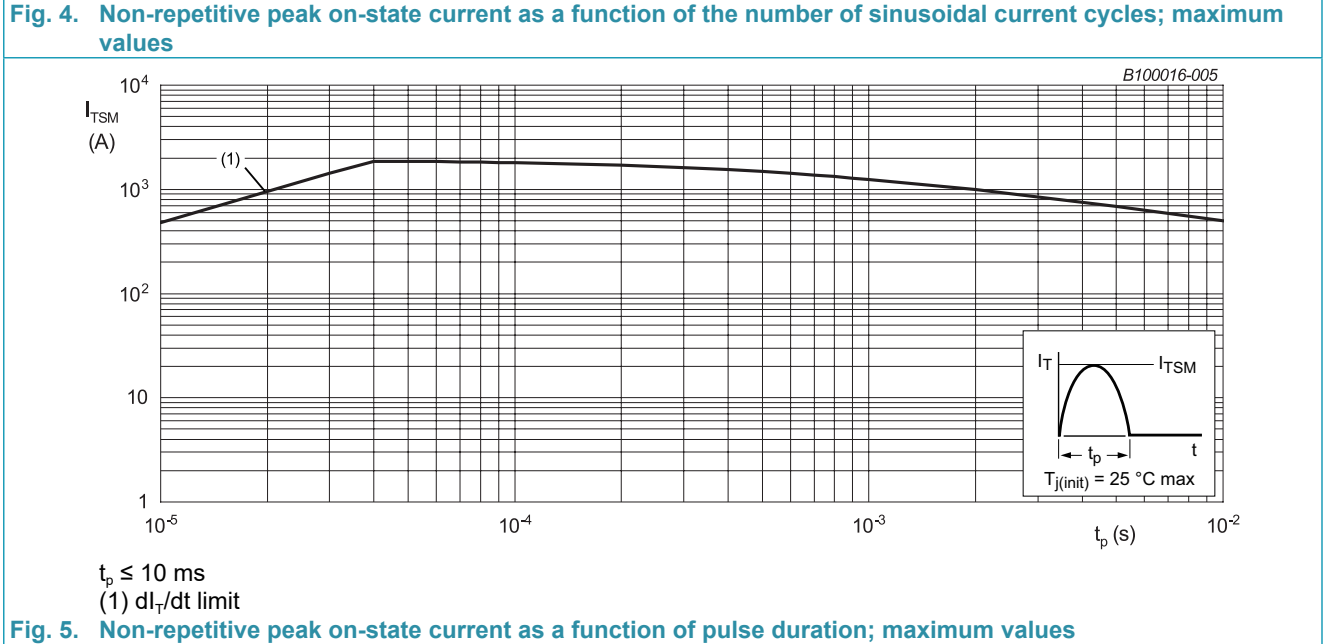
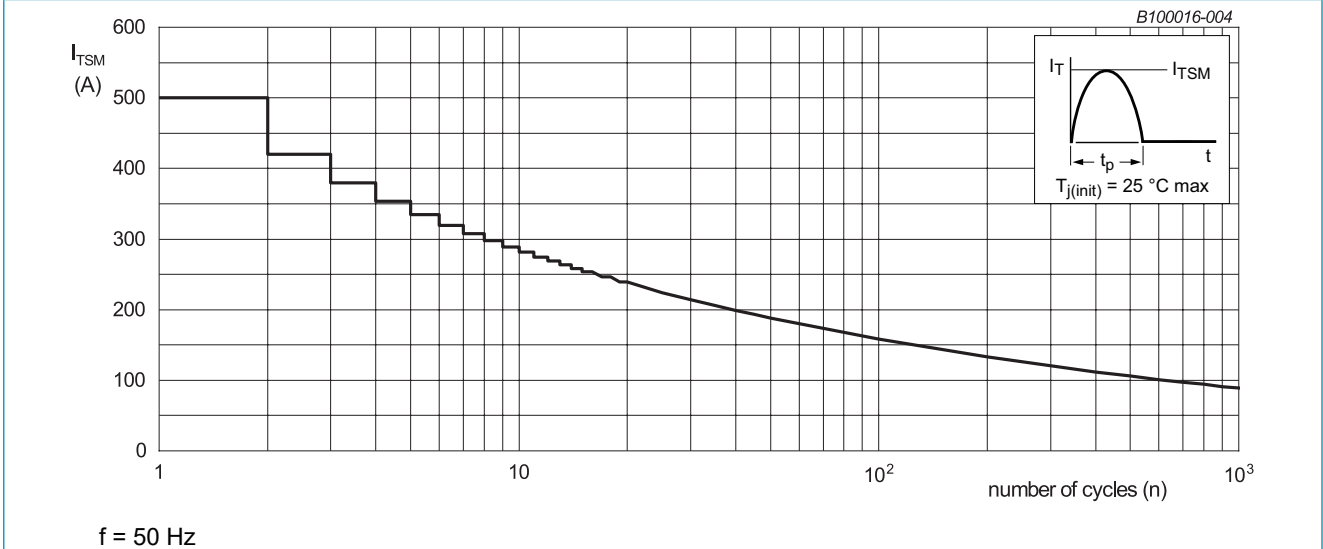
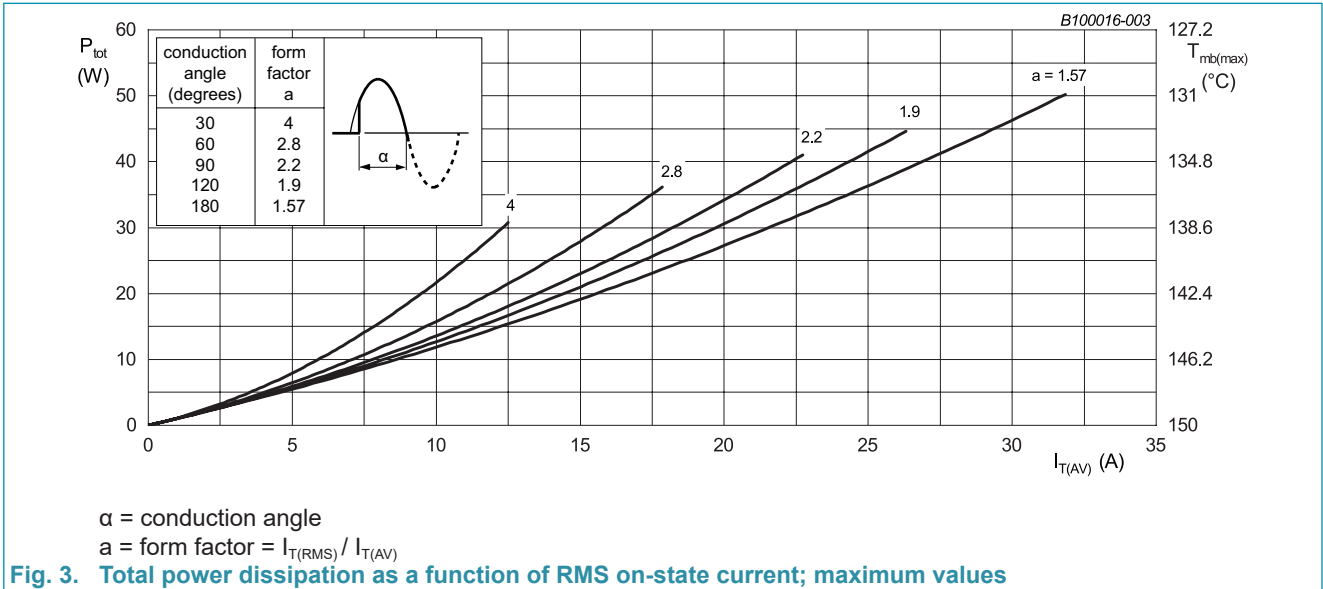
8. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Notes	Values	Unit
V_{DRM}	repetitive peak off-state voltage			800	V
V_{RRM}	repetitive peak reverse voltage			800	V
$I_{T(AV)}$	average on-state current	half sine wave; $T_{mb} \leq 131\text{ °C}$;		32	A
$I_{T(RMS)}$	RMS on-state current	half sine wave; $T_{mb} \leq 131\text{ °C}$; Fig. 1 ; Fig. 2 ; Fig. 3		50	A
I_{TSM}	non-repetitive peak on-state current	half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 10\text{ ms}$; Fig. 4 ; Fig. 5		500	A
		half sine wave; $T_{j(init)} = 25\text{ °C}$; $t_p = 8.3\text{ ms}$		550	A
I^2t	I^2t for fusing	$t_p = 10\text{ ms}$; sine-wave pulse		1250	A ² s
di_T/dt	rate of rise of on-state current	$I_G = 30\text{ mA}$		150	A/ μ s
I_{GM}	peak gate current			5	A
V_{GM}	peak gate voltage			5	V
V_{GRM}	peak reverse gate voltage			7	V
P_{GM}	peak gate power			20	W
$P_{G(AV)}$	average gate power	over any 20 ms period		1	W
T_{stg}	storage temperature			-40 to 150	°C
T_j	junction temperature			-40 to 150	°C





9. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
$R_{th(j-mb)}$	thermal resistance from junction to mounting base	Fig. 6		-	-	0.38	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		-	60	-	K/W

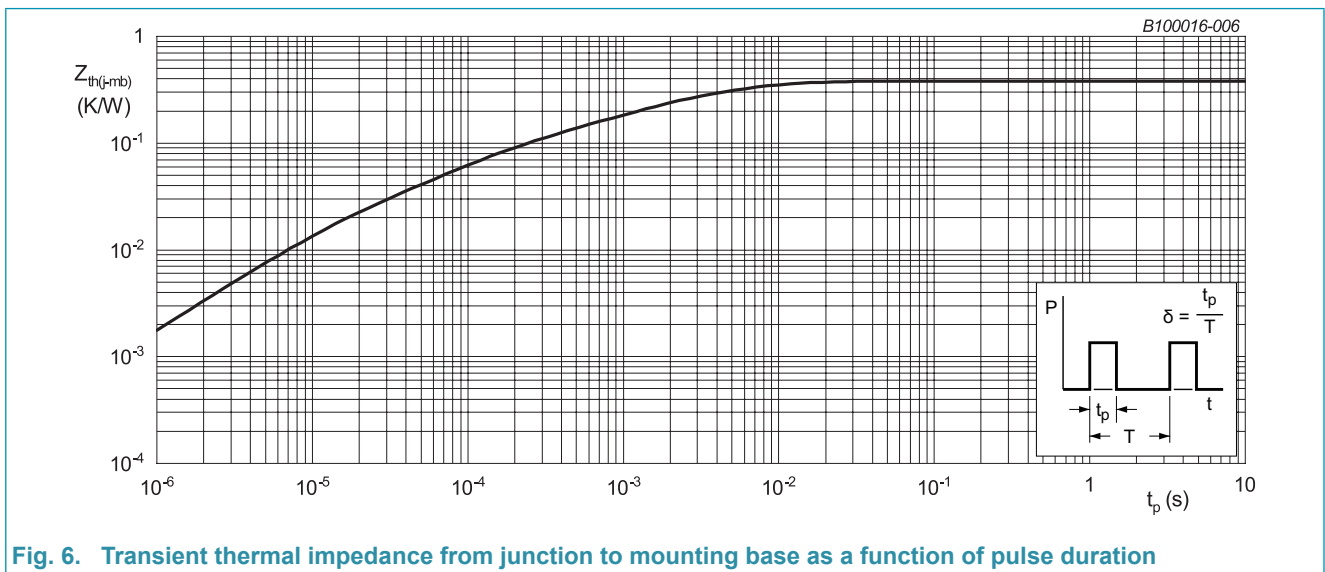
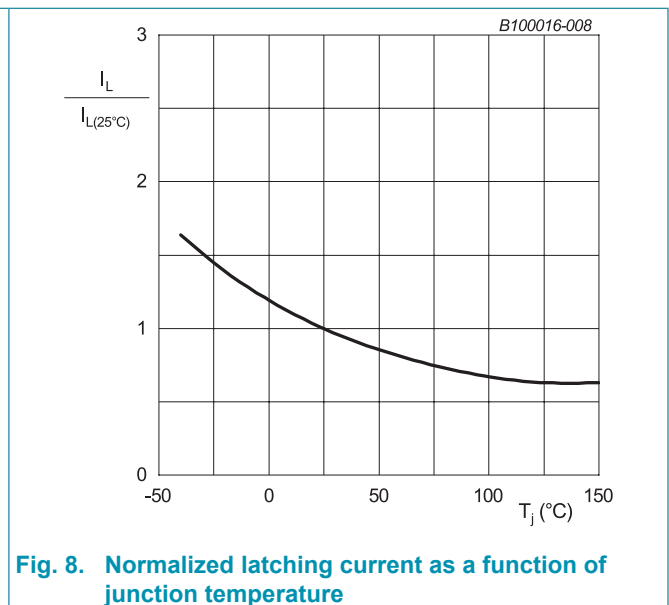
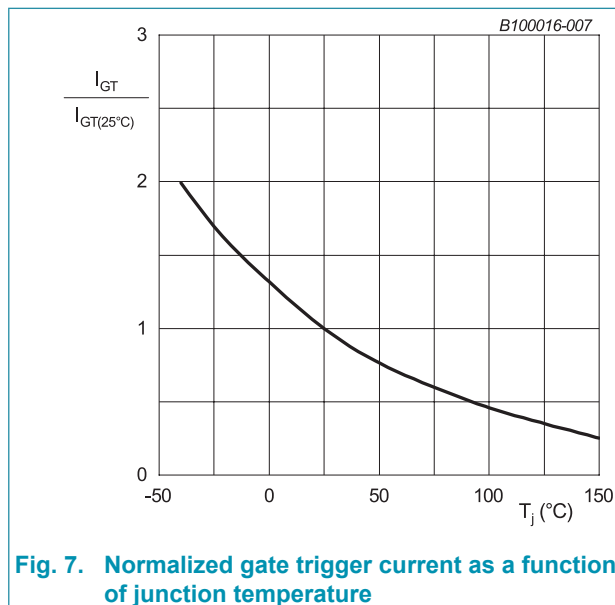


Fig. 6. Transient thermal impedance from junction to mounting base as a function of pulse duration

10. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Notes	Min	Typ	Max	Unit
Static characteristics							
I_{GT}	gate trigger current	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 7		-	-	15	mA
I_L	latching current	$V_D = 12\text{ V}$; $I_G = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 8		-	-	80	mA
I_H	holding current	$V_D = 12\text{ V}$; $T_j = 25\text{ °C}$; Fig. 9		-	-	60	mA
V_T	on-state voltage	$I_T = 100\text{ A}$; $T_j = 25\text{ °C}$; Fig. 10		-	-	1.65	V
V_{GT}	gate trigger voltage	$V_D = 12\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 25\text{ °C}$; Fig. 11		-	0.7	1.2	V
		$V_D = 400\text{ V}$; $I_T = 0.1\text{ A}$; $T_j = 150\text{ °C}$		0.25	0.5	-	V
I_D	off-state current	$V_D = 800\text{ V}$; $T_j = 25\text{ °C}$		-	-	5	μA
		$V_D = 800\text{ V}$; $T_j = 150\text{ °C}$		-	-	2	mA
I_R	reverse current	$V_D = 800\text{ V}$; $T_j = 25\text{ °C}$		-	-	5	μA
		$V_D = 800\text{ V}$; $T_j = 150\text{ °C}$		-	-	2	mA
Dynamic characteristics							
dV_D/dt	rate of rise of off-state voltage	$V_{DM} = 536\text{ V}$; $T_j = 150\text{ °C}$; ($V_{DM} = 67\%$ of V_{DRM}); exponential waveform; gate open circuit		500	-	-	V/ μs
t_{gt}	gate-controlled turn-on time	$I_{TM} = 50\text{ A}$; $V_D = 800\text{ V}$; $I_G = 30\text{ mA}$; $dI_G/dt = 5\text{ A}/\mu\text{s}$; $T_j = 25\text{ °C}$		-	2	-	μs
t_q	commutated turn-off time	$I_{TM} = 2\text{ A}$; $t_p = 50\text{ }\mu\text{s}$; $dV/dt = 5\text{ V}/\mu\text{s}$; $dI/dt = 30\text{ A}/\mu\text{s}$; $T_j = 25\text{ °C}$		-	-	25	μs



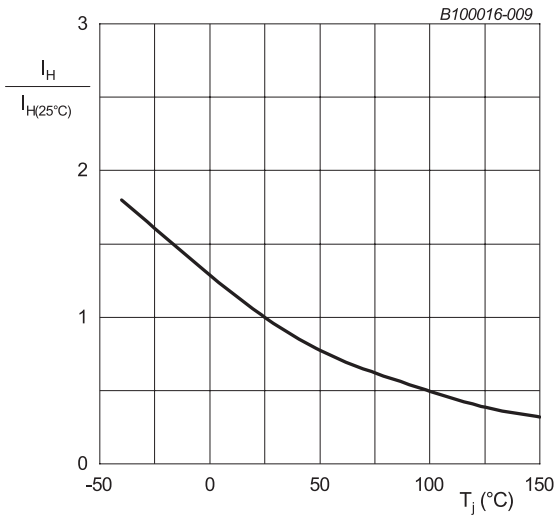
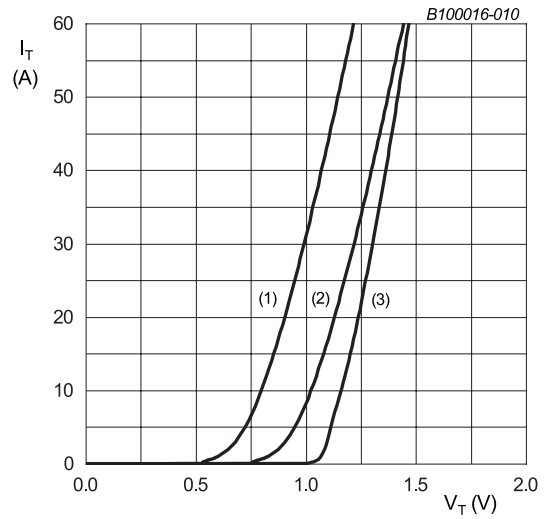


Fig. 9. Normalized holding current as a function of junction temperature



$V_o = 1.006 \text{ V}$; $R_s = 0.0073 \Omega$
 (1) $T_j = 150 \text{ }^\circ\text{C}$; typical values
 (2) $T_j = 150 \text{ }^\circ\text{C}$; maximum values
 (3) $T_j = 25 \text{ }^\circ\text{C}$; maximum values

Fig. 10. On-state current as a function of on-state voltage

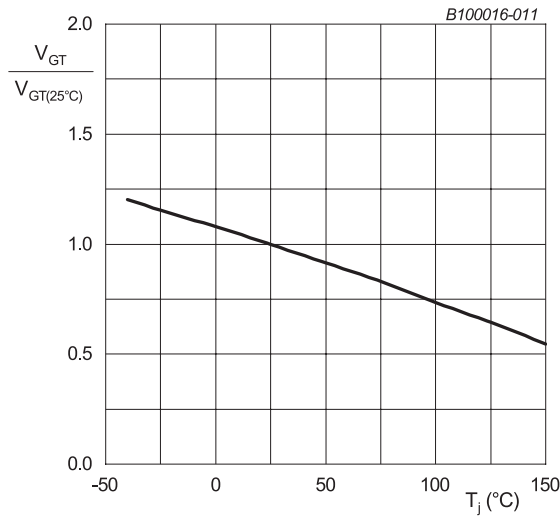
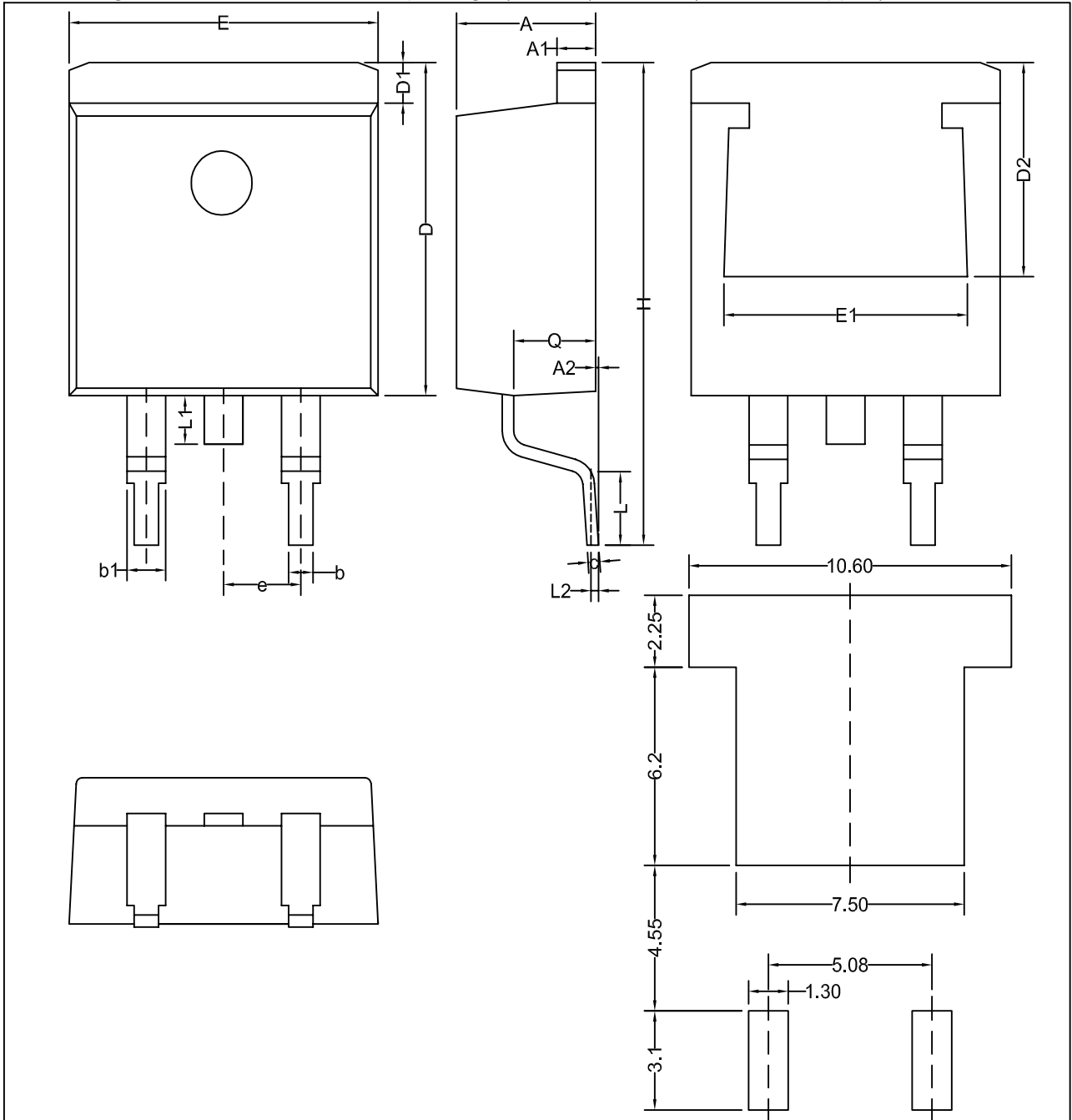


Fig. 11. Normalized gate trigger voltage as a function of junction temperature

11. Package outline

Plastic single-ended surface-mounted package (D2PAK); 3 leads (one lead cropped) TO263



Recommended Footprint

Unit	A	A1	A2	b	b1	c	D	D1	D2	e	E	E1	H	L	L1	L2	Q
min	4.10	1.22	0.00	0.60	1.05	0.34	---	1.20	6.60	2.54 (BSC)	9.70	7.80	14.80	2.10	---	0.25 (BSC)	2.20
max	4.70	1.40	0.25	0.90	1.45	0.64	11.00	1.60	---	---	10.30	---	15.80	2.90	1.75	---	2.79

12. Legal information

Data sheet status

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
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- [2] The term 'short data sheet' is explained in section "Definitions".
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